LNA4905L

GaAlAs Infrared Light Emitting Diode

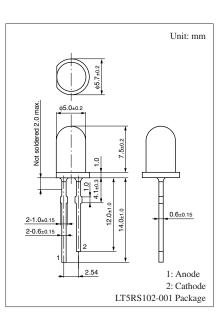
For optical control systems

Features

- High output power, high-efficiency: $P_0 = 15 \text{ mW} \text{ (min.)}$
- Fast response and high-speed modulation capability: $f_C = 30 \text{ MHz} \text{ (typ.)}$
- Transparent epoxy resin package

Absolute Maximum Hatings $T_a = 25$ C							
Symbol Rating		Unit					
V _R	3	V					
$I_{\rm F}$	100	mA					
I_{FP}	1	А					
P _D	190	mW					
T _{opr}	-25 to +85	°C					
T _{stg}	-30 to +100	°C					
	Symbol V _R I _F P _D T _{opr}	$\begin{tabular}{ c c c c } \hline Symbol & Rating \\ \hline V_R & 3 \\ \hline I_F & 100 \\ \hline I_{FP} & 1 \\ \hline P_D & 190 \\ \hline T_{opr} & -25 \text{ to } +85 \\ \hline \end{tabular}$					

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Note) *: f = 100 Hz, Duty Cycle = 0.1%

Electrical-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_{\rm F} = 100 \ {\rm mA}$		1.7	2.1	V
Reverse current	I _R	$V_R = 3 V$			10	μΑ
Radiant power	Po	$I_F = 50 \text{ mA}$	15			mW
Peak emission wavelength	$\lambda_{\rm P}$	$I_F = 50 \text{ mA}$		880		nm
Spectral half band width	Δλ	$I_F = 50 \text{ mA}$		50		nm
Half-power angle	θ	The angle when the radiant power is halved		15		0

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

$$f_C: 10 \times \log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 1 \text{ MHz}} = -3$$

3. A light detection element uses a silicon diode have proofread a load with a standard device.

4. LED might radiate red light under large current drive.

▲ Caution for Safety

⚠ DANGER

This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded form general industrial waste or household garbage.

Request for your special attention and precautions in using the technical information and semiconductors described in this material

- (1) An export permit needs to be obtained from the competent authorities of the Japanese Government if any of the products or technical information described in this material and controlled under the "Foreign Exchange and Foreign Trade Law" is to be exported or taken out of Japan.
- (2) The technical information described in this material is limited to showing representative characteristics and applied circuits examples of the products. It neither warrants non-infringement of intellectual property right or any other rights owned by our company or a third party, nor grants any license.
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